ABSTRACT OF THE DISCLOSURE

HIGH PERFORMANCE INTEGRATED CIRCUIT CHIP PACKAGE

A high performance IC package provides high density electrical interconnection and packaging for a high speed and high bandwidth IC chip and is easily connected to or disconnected from a printed circuit board. The IC package includes an enclosure; an integrated circuit chip having a front face and a back face wherein the back face is attached to an inner ceiling of the enclosure; contacts formed on die pads on the front face through a photolithography process where each of the contacts has a base portion vertically formed on the die pad, a horizontal portion whose one end is formed on the base portion, and a contact portion vertically formed on another end of the horizontal portion; and an encapsulant provided on the front face of the integrated circuit chip for air tightly sealing. The contacts are projected through the encapsulant, and the horizontal portion of each of the contacts produces a contact force when the contact is pressed against a contact target.

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